

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC9260xxxxER-G
Typical Mass: 6 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number | |
|--------------|------------|---------------|--------------|------------|------------|
| Silicon chip | 0.648 | Silicon | 108000 | 7440-21-3 | |
| | | - Arsenic | <1 | 7440-38-2 | |
| Lead pad | 1.100 | Nickel | 183400 | 7440-02-0 | |
| | | 0.087 | Silver | 14600 | 7440-22-4 |
| | | 0.016 | Gold | 2700 | 7440-57-5 |
| Die attach | 0.020 | Epoxy Resin | 3300 | — | |
| | | 0.016 | Silica | 2700 | 60676-86-0 |
| Bonding wire | 0.208 | Gold | 34700 | 7440-57-5 | |
| Resin | 3.513 | Silica | 585500 | 60676-86-0 | |
| | | 0.215 | Epoxy Resin | 35800 | — |
| | | 0.176 | Phenol Resin | 29300 | — |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."